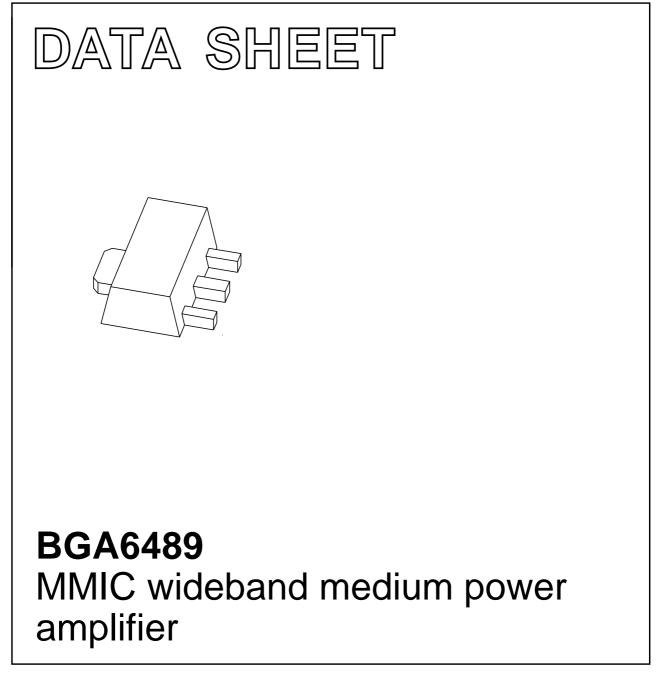
DISCRETE SEMICONDUCTORS



Product specification

2003 Sep 18



BGA6489

FEATURES

- Broadband 50 Ω gain block
- 20 dBm output power
- SOT89 package
- Single supply voltage needed.

APPLICATIONS

- · Broadband medium power gain blocks
- · Small signal high linearity amplifiers
- · Variable gain and high output power in combination with the BGA2031
- Cellular, PCS and CDPD
- IF/RF buffer amplifier
- Wireless data SONET
- · Oscillator amplifier, final PA
- Drivers for CATV amplifier.

DESCRIPTION

Silicon Monolithic Microwave Integrated Circuit (MMIC) wideband medium power amplifier with internal matching circuit in a 4-pin SOT89 plastic low thermal resistance SMD package.

The BGA6x89 series of medium power gain blocks are resistive feedback Darlington configured amplifiers. Resistive feedback provides large bandwidth with high accuracy.

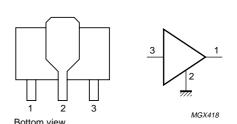
QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS		UNIT
Vs	DC supply voltage	I _S = 74 mA	5.1	V
I _S	DC supply current	$V_{S} = 8 \text{ V}; \text{ R1} = 39 \Omega; \text{ T}_{j} = 25 ^{\circ}\text{C}$	78	mA
s ₂₁ ²	insertion power gain	f = 1.95 GHz	16	dB
NF	noise figure	f = 1.95 GHz	3.3	dB
P _{L 1 dB}	load power at 1 dB compression	f = 850 MHz	20	dBm
		f = 1.95 GHz	17	dBm

CAUTION

This product is supplied in anti-static packing to prevent damage caused by electrostatic discharge during transport and handling. For further information, refer to Philips specs.: SNW-EQ-608, SNW-FQ-302A and SNW-FQ-302B.

PIN	DESCRIPTION
1	RF out/bias
2	GND
3	RF in



Bottom view

Marking code: 4A.

PINNING

Fig.1 Simplified outline (SOT89) and symbol.

BGA6489

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134)

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
Vs	DC supply voltage	RF input AC coupled	_	6	V
I _S	DC supply current		_	150	mA
P _{tot}	total power dissipation	$T_s \le 70 \ ^{\circ}C$; note 1	-	800	mW
T _{stg}	storage temperature		-65	+150	°C
Tj	operating junction temperature		-	150	°C
PD	maximum drive power		-	15	dBm

Note

1. T_s is the temperature at the soldering point of pin 2.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th j-s}	thermal resistance from junction to solder point	$T_s \le 70 \ ^{\circ}C$; note 1	100	K/W

Note

1. T_s is the temperature at the soldering point of pin 2.

STATIC CHARACTERISTICS

 T_{i} = 25 °C; V_{S} = 8 V; R1 = 39 $\Omega;$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _S	supply current		70	78	86	mA

BGA6489

CHARACTERISTICS

 $V_S = 8 \text{ V}$; $I_S = 74 \text{ mA}$; $T_{amb} = 25 \text{ °C}$; $IP3_{(out)}$ tone spacing = 1 MHz; $P_L = 0 \text{ dBm}$ per tone (see Fig.2); $R1 = 39 \Omega$; $Z_L = Z_S = 50 \Omega$; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	TYP.	UNIT
s ₂₁ ²	insertion power gain	f = 850 MHz	20	dB
		f = 1.95 GHz	16	dB
		f = 2.5 GHz	15	dB
R _{L IN}	return losses input	f = 850 MHz	14	dB
		f = 1.95 GHz	16	dB
		f = 2.5 GHz	19	dB
R _{L OUT}	return losses output	f = 850 MHz	16	dB
		f = 1.95 GHz	12	dB
		f = 2.5 GHz	10	dB
NF	noise figure	f = 850 MHz	3.1	dB
		f = 1.95 GHz	3.3	dB
		f = 2.5 GHz	3.4	dB
К	stability factor	f = 850 MHz	1.2	-
		f = 2.5 GHz	1.3	-
P _{L 1 dB}	load power	at 1 dB gain compression; f = 850 MHz	20	dBm
		at 1 dB gain compression; f = 1.95 GHz	17	dBm
IP3 _(in)	input intercept point	f = 850 MHz	13	dBm
		f = 2.5 GHz	12	dBm
IP3 _(out)	output intercept point	f = 850 MHz	33	dBm
		f = 2.5 GHz	27	dBm

Product specification

MMIC wideband medium power amplifier

BGA6489

APPLICATION INFORMATION

Figure 2 shows a typical application circuit for the BGA6489 MMIC. The device is internally matched to 50 Ω , and therefore does not require any external matching. The value of the input and output DC blocking capacitors C1 and C2 depends on the operating frequency; see the tables below. Capacitors C1 and C2 are used in conjunction with L1 and C3 to fine tune the input and output impedance. For optimum supply decoupling, a 1 μ F capacitor (C5) can be added. The external components should be placed as close as possible to the MMIC. When using via holes, use multiple via holes per pin in order to limit ground path induction. Resistor R1 is a bias resistor providing DC current stability with temperature.

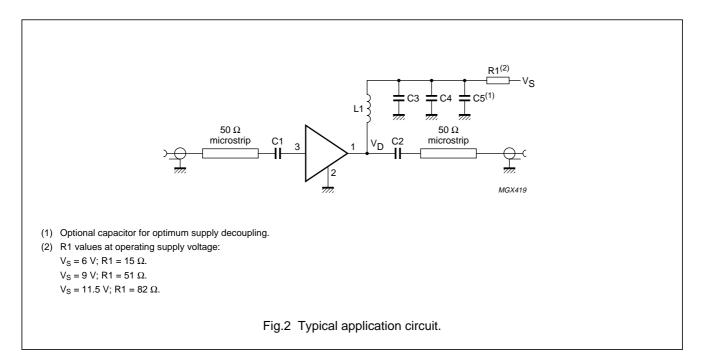
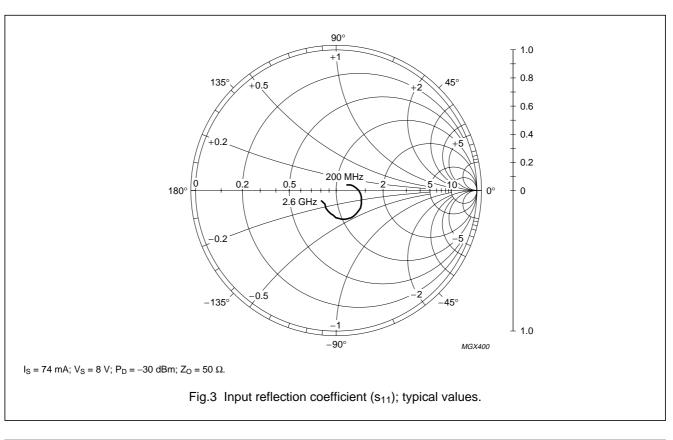
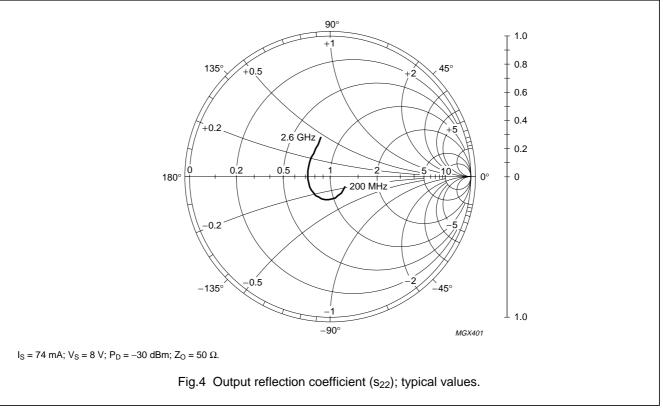
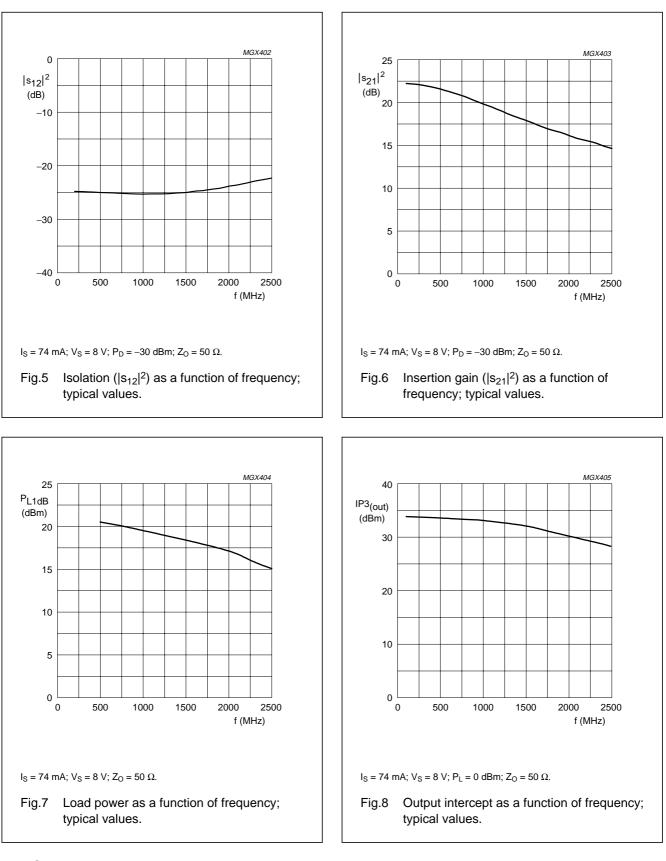


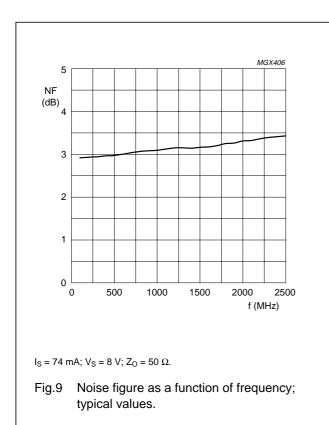
Table 1 Component descriptions (see Fig.2)

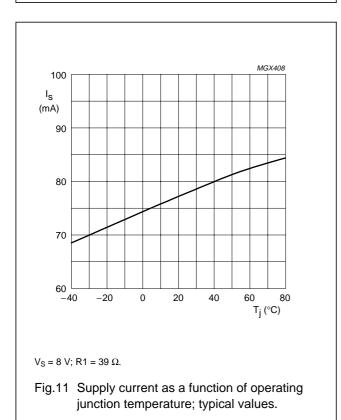
			VALUE AT OPERATING FREQUENCY					
COMPONENT	DESCRIPTION	DIMENSIONS	500 MHz	800 MHz	1950 MHz	2400 MHz	3500 MHz	
C1, C2	multilayer ceramic chip capacitor	0603	220 pF	100 pF	68 pF	56 pF	39 pF	
C3	multilayer ceramic chip capacitor	0603	1 nF	1 nF	1 nF	1 nF	1 nF	
C4	multilayer ceramic chip capacitor	0603	100 pF	68 pF	22 pF	22 pF	15 pF	
C5 (optional)	electrolytic or tantalum capacitor	0603	1 μF	1 μF	1 μF	1 μF	1 μF	
L1	SMD inductor	0603	68 nH	33 nH	22 nH	18 nH	15 nH	
R1	SMD resistor 0.5 W; $V_S = 9 V$	_	_	_	_	_	_	

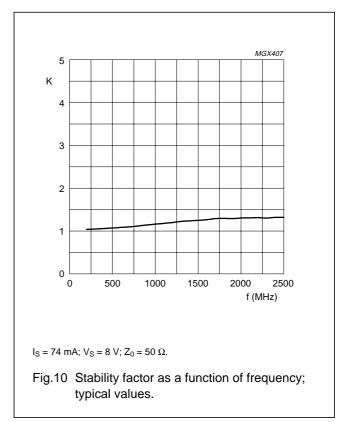












Scattering parameters

V _S = 8 V; I _S = 74	mA; $P_D = -30 \text{ dBm}$; Z	$Z_{\rm O} = 50 \ \Omega; \ T_{\rm amb} = 25 \ ^{\circ}{\rm C}$

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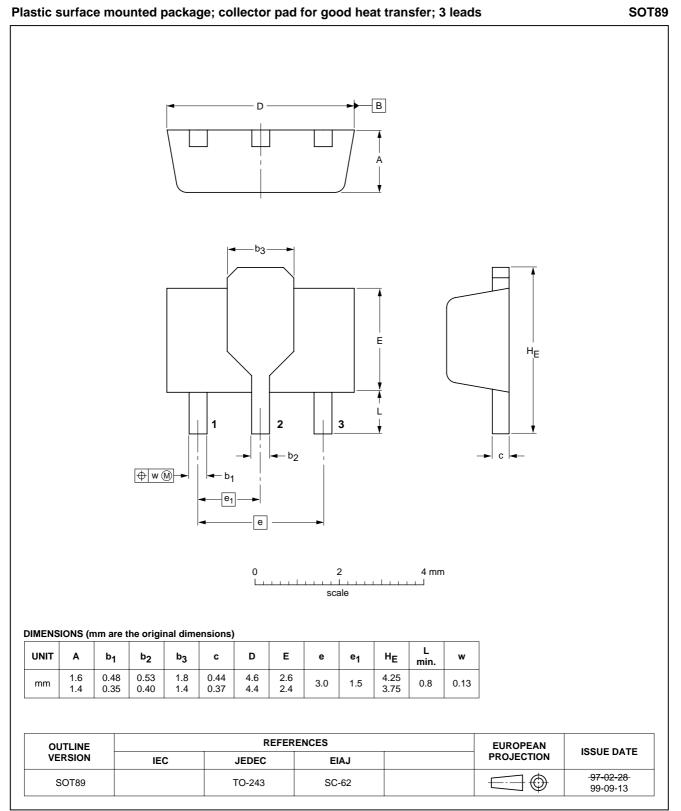
	S ₁₁		s ₂₁		S ₁₂		S ₂₂		
f (MHz)	MAGNITUDE (ratio)	ANGLE (deg)	MAGNITUDE (ratio)	ANGLE (deg)	MAGNITUDE (ratio)	ANGLE (deg)	MAGNITUDE (ratio)	ANGLE (deg)	K-FACTOR
200	0.06	28.11	12.79	164.42	0.06	-0.30	0.12	-22.91	1.1
300	0.09	27.41	12.59	156.85	0.06	-0.39	0.13	-35.38	1.1
400	0.11	21.64	12.31	149.28	0.06	-0.35	0.14	-46.54	1.1
500	0.12	15.28	11.97	141.88	0.06	-0.32	0.14	-57.20	1.1
600	0.14	8.01	11.57	134.79	0.06	0.04	0.15	-61.41	1.1
700	0.16	0.34	11.18	127.97	0.06	0.63	0.16	-76.76	1.1
800	0.17	-7.27	10.75	121.56	0.05	1.57	0.16	-85.75	1.2
900	0.18	-14.78	10.24	115.06	0.05	1.85	0.17	-94.28	1.2
1000	0.19	-22.18	9.80	109.18	0.05	3.16	0.17	-102.4	1.2
1100	0.20	-29.33	9.40	103.40	0.05	4.29	0.17	-110.3	1.2
1200	0.21	-36.41	8.96	98.12	0.05	5.64	0.17	-118.5	1.2
1300	0.21	-42.47	8.53	92.76	0.05	7.03	0.17	-126.7	1.2
1400	0.22	-49.06	8.16	87.50	0.06	7.74	0.17	-134.8	1.2
1500	0.22	-55.46	7.85	82.76	0.06	9.08	0.17	-143.5	1.3
1600	0.22	-61.20	7.51	78.52	0.06	10.76	0.16	-152.7	1.3
1700	0.22	-67.02	7.16	74.16	0.06	11.89	0.16	-161.8	1.3
1800	0.21	-73.40	6.90	69.37	0.06	12.34	0.16	-171.9	1.3
1900	0.21	-78.99	6.69	65.14	0.06	13.16	0.16	177.4	1.3
2000	0.20	-84.54	6.42	61.15	0.06	14.33	0.16	166.81	1.3
2100	0.19	-91.32	6.16	56.80	0.07	14.84	0.17	156.07	1.3
2200	0.18	-97.58	5.99	52.55	0.07	15.05	0.17	145.29	1.3
2300	0.17	-103.60	5.83	49.08	0.07	15.72	0.19	135.65	1.3
2400	0.16	-111.90	5.58	45.43	0.07	15.96	0.20	126.23	1.3
2500	0.14	-120.80	5.39	40.67	0.08	15.27	0.22	117.62	1.3
2600	0.13	-129.80	5.30	36.66	0.08	14.68	0.24	110.35	1.3
2700	0.13	-143.80	5.18	33.88	0.08	15.64	0.28	104.05	1.3
2800	0.12	-154.47	5.08	30.28	0.08	15.56	0.31	97.10	1.3
2900	0.11	-164.40	4.71	22.43	0.09	11.60	0.28	91.75	1.3
3000	0.11	178.65	4.66	18.90	0.09	11.05	0.31	84.80	1.3
3100	0.12	160.01	4.45	18.63	0.10	10.63	0.33	80.37	1.3

MMIC wideband medium power amplifier

BGA6489

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PACKAGE OUTLINE



BGA6489

DATA SHEET STATUS

LEVEL	DATA SHEET STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾⁽³⁾	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
11	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
	Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN).

Notes

- 1. Please consult the most recently issued data sheet before initiating or completing a design.
- 2. The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.
- 3. For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

DEFINITIONS

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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